



Material Content Data Sheet



Sales Product Name	BSR315P H6327			Issued		4. February 2020		
MA#	MA001307956							
Package	PG-SC59-3-3			Weight*		13.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.008	0.06		604	
	noble metal	gold	7440-57-5	0.032	0.23		2341	
	inorganic material	silicon	7440-21-3	0.367	2.65	2.94	26533	29478
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		81	
	non noble metal	titanium	7440-32-6	0.006	0.04		404	
	non noble metal	chromium	7440-47-3	0.017	0.12		1213	
	non noble metal	copper	7440-50-8	5.564	40.28	40.45	402789	404487
wire	non noble metal	copper	7440-50-8	0.044	0.32	0.32	3152	3152
encapsulation	organic material	carbon black	1333-86-4	0.073	0.53		5321	
	plastics	epoxy resin	-	1.580	11.44		114394	
	inorganic material	silicondioxide	60676-86-0	5.696	41.24	53.21	412349	532064
leadfinish	non noble metal	tin	7440-31-5	0.258	1.87	1.87	18686	18686
plating	noble metal	silver	7440-22-4	0.168	1.21	1.21	12133	12133
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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